Customer Information Notification | 201607020I

Issue Date: 09-Sep-2016
Effective Date: 10-Sep-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

QUALITY

Management Summary
MPC5777M Reference Manual Update

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[X] Electrical spec./Test coverage

MPC5777M Reference Manual Update

Information Notification

The MPC5777M Reference Manual has been updated to include addendum revision 4.2.

The MPC5777M Reference Manual can be found at http://www.nxp.com/MPC5777M.

Why do we issue this Information Notification
The MPC5777M Reference Manual has been updated to correct errors and provide additional technical clarification on some device features.

Identification of Affected Products
Product identification does not change

Impact

no impact to the product's functionality anticipated.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name   Randy Dees
Position   Applications Engineer
e-mail address   randy.dees@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	New Orderable Part#	New part 12NC	New Part number	New part description	Product Line
SPC5777MK0MVA8	SPC5777MK0MVA8	SPC5777MK0MVA8	QUAD CORE 8M FLASH 404K	TEPBGA 512 25*25*2.1 P.8	TEPBGA 512 25*25*2.1 P.8	RFS	SPC5777MK0MVA8	SPC5777MK0MVA8	SPC5777MK0MVA8	QUAD CORE 8M FLASH 404K	BL Auto Processors
SPC5777MK0MVU8	SPC5777MK0MVU8	SPC5777MK0MVU8	QUAD CORE 8M FLASH	TEPBGA 416 27*27*1.25 P1	TEPBGA 416 27*27*1.25 P1	RFS	SPC5777MK0MVU8	SPC5777MK0MVU8	SPC5777MK0MVU8	QUAD CORE 8M FLASH	BL Auto Processors